

Modular Placement Machine

- Capable of supporting a wide range of components from microchips to CSPs and connectors
- Maximum productivity

			BM231
MODEL NUMBER			NM-MF13
PCB DIMENSIONS		Min L x W to Max L x W	50 mm x 50 mm 510 mm x 460 mm
MAXIMUM SPEED*1			0.25 s/chip
PLACEMENT ACCURACY*1		Chip QFP	50 μm (Cp≥1) 30 μm (Cp≥1)
NUMBER OF COMPONENT INPUTS		Double tape feeder Tray feeder	120 80
COMPONENT DIMENSIONS*2			0603 chip – L 150 mm x W 25 mm x T 25 mm
PCB EXCHANGE TIME*3			5.0 s
ELECTRIC SOURCE*4			3-phase AC 200 V, 3.3 kVA
PNEUMATIC SOURCE			0.43 MPa, 150 L/min (A.N.R.)
DIMENSIONS		W D H	1,950 mm 2,270 mm*5 1,500 mm*6
MASS*7			2,100 kg (fixed supply specification)

*1 May differ between components

*2 Consult your sales representative for more information

*3 Determined by board dimensions

*4 Compatible with 220/380/400/420/480V

note: Values such as maximum speed and placement accuracy may vary depending on operating conditions.
Please refer to the detail specifications.

*5 Excluding batch exchange cart and tape feeder

*6 Excluding rec monitor and signal tower

*7 2,300 kg including package batch exchange cart